RENESAS

RJU1CF01DWA / RJU1CF01DWS

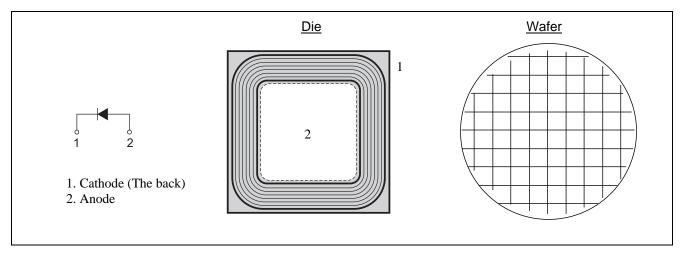
1250V - 15A - Fast Recovery Diode Application: Inverter

R07DS1473EJ0201 Rev.2.01 Apr.10.2020

Features

- Low forward voltage $V_F = 2.3 \text{ V}$ typ. (at $I_F = 15 \text{ A}$, $Tc = 25^{\circ}C$)
- Fast Recovery (soft recovery)
 - $t_{rr} = 40$ ns typ. (at I_F = 15 A, di/dt = 1500 A/µs, Tc = 25°C)

Outline



Absolute Maximum Ratings

 $(Tc = 25^{\circ}C \text{ unless otherwise noted})$

ltem		Symbol	Ratings	Unit
Maximum reverse voltage		V _{RM}	1250	V
Forward current	Tc = 25°C	IF Notes1	30	А
	Tc = 100°C	IF Notes1	15	А
Junction temperature		Tj ^{Notes2}	175	°C

Notes: 1. Depends on thermal properties of assembly.

2. Please use this device in the thermal condition which the junction temperature does not exceed 175 °C. IGBT Application Note is disclosed about reliability test and application condition up to Tj = 175 °C.

Continuous heavy condition (e.g. high temperature/voltage/current or high variation of temperature) may
affect a reliability even if it is within the absolute maximum ratings. Please consider derating condition for
appropriate reliability in reference Renesas Semiconductor Reliability Handbook (Recommendation for
Handling and Usage of Semiconductor Devices) and individual reliability data.



Electrical Characteristics (These data are an actual measurement value in a package.)

 $(Tc = 25^{\circ}C \text{ unless otherwise noted})$

ltem	Symbol	Min	Тур	Max	Unit	Test conditions
Forward voltage	VF		2.3	2.8	V	I _F = 15 A ^{Notes4, Notes5}
Reverse current	IR		_	25	μA	$V_R = 1250 V^{Notes6}$
Reverse recovery time	trr		40		ns	I _F = 15 A, di/dt = 1500 A/μs _{Notes5, Notes7}

Note2: Pulse test

Notes: 4. Pulse test

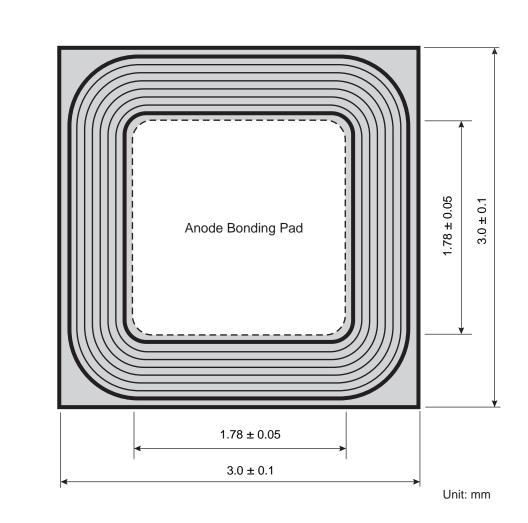
5. Designed target value on Renesas measurement condition. (Not tested)

6. Tested on wafer

7. Tested to be mounted on Renesas single test vehicle.



Die Dimension



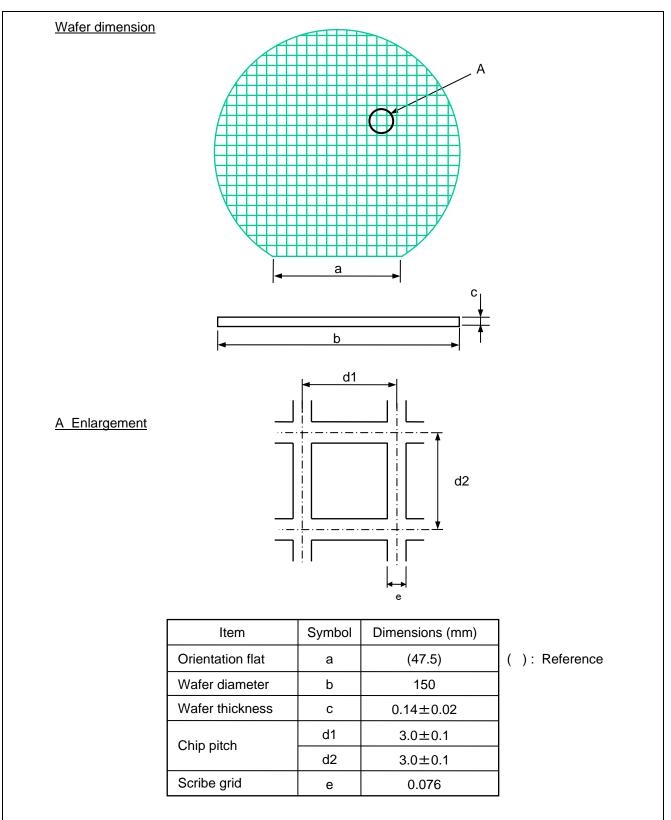
Notes 1.

Illustration	Definition		
Part of white	Al pattern		
Part of dotted line	Bonding area		
Part of gray	Final passivation		

- 2. The back of the chip is processed with Au evaporation.
- 3. Recognition, target and any other patterns which are not related to Diode operation, may be changed without notice.



Wafer Dimension



Ordering Information

Orderable Part Number	Shipment form		
RJU1CF01DWA-00#W0	Unsawn wafer		
RJU1CF01DWS-00#W0	Sawn wafer		



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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan

Contact Information

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